

Gold Plating

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Common Name	Also Known as	Typical Bath Constituents	Power Supply Recommendations	Typical Pulse Settings (if Used)	Typical Operating Parameters
Sulfite Gold	Soft Gold	Gold (1.2-1.5 tr. oz/Gal)	<1% ripple	High Frequency (HFP); Do Not Use Low Frequency Pulse (LFP)	Anodes: Platinum-Clad Columbium or Titanium (316 SS may be used if deposit purity isn't critical)
		Stabilizer (20g/Gal)	Amp-hr meter (gold metal additions based on A-hr meter readings)	Duty Cycle: 10% on a resistive seed layer or 70% on conductive metal	Heaters: Derated Titanium, Quartz, 316 SS
		Sodium Sulfite (45 g/L)	Pulse Recommended	10% Duty Cycle: 0.1 ms ON Time 70% Duty Cycle: 0.7 ms ON Time	Filter Continuously
			Totalizer (tracks gold usage to prevent misuse or theft)	10% Duty Cycle: 0.9 ms OFF Time 70% Duty Cycle: 0.3 ms ON Time	Carbon Treat (Sensitive to Organics)
					Agitation: Moderate to Vigorous
					Operating temp: 110 to 160 F (140 F Nominal)
					Typical pH (range): 6 to 7
					Output Voltage (Power Supply Max Rating): 6 VDC
					Current Density: 1-8 ASF (0.1-0.8 ASD)